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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10075043	FILING DATE 02/12/2002	CLASS 438	SUBCLASS -	GAU 2812	EXAMINER <i>[Signature]</i>
**APPLICANTS: Tseng David; Huang Chien-Ping; Huang Kun-Ming;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: TAIWAN TW 90133149 12/31/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		56956 (71987)			
TITLE : Method and system of wire bonding for use in fabrication of semiconductor package <small>U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)</small>					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
Assistant Examiner		DRAWING	
		Sheets Drwg.	Figs. Drwg.
		Print Fig.	
Primary Examiner		Application Examiner	
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